**ODCSP35 3.39x3.44**
CASE 570CM
ISSUE A

DATE 01 AUG 2019
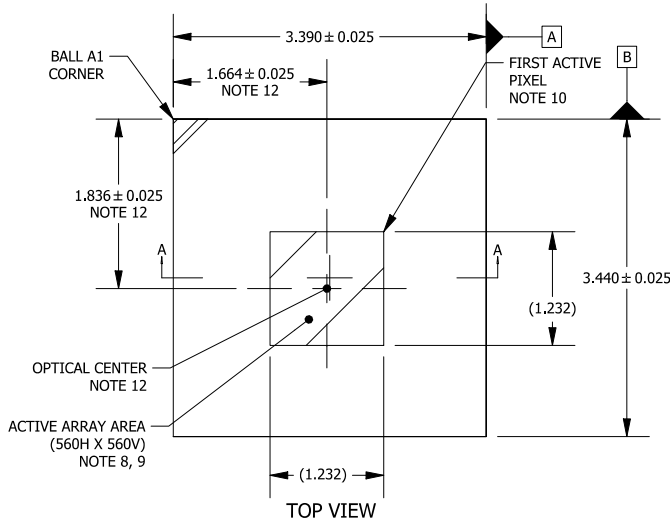
NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS [mm].
3. SOLDER BALL DIAMETER IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER PARALLEL TO DATUM C.
4. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. DATUM C, THE SEATING PLANE IS DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
6. GLASS: 0.400 THICKNESS; REFRACTIVE INDEX = 1.52.
7. AIR GAP BETWEEN GLASS AND PIXEL ARRAY: 0.044 THICKNESS.
8. PARALLELISM APPLIES ONLY TO THE ACTIVE ARRAY.
9. MAXIMUM ROTATION OF ACTIVE ARRAY RELATIVE TO DATUMS A AND B IS ± 0.1°.
10. REFER TO THE DEVICE DATA SHEET FOR TOTAL PIXEL ARRAY DEFINITIONS.
11. PACKAGE CENTER (X, Y) = (0.000, 0.000).
12. OPTICAL CENTER RELATIVE TO PACKAGE CENTER (X, Y) = (-0.031, -0.116).

TOP VIEW

SECTION A-A

DETAIL B

BOTTOM VIEW

RECOMENDED MOUNTING FOOTPRINT*
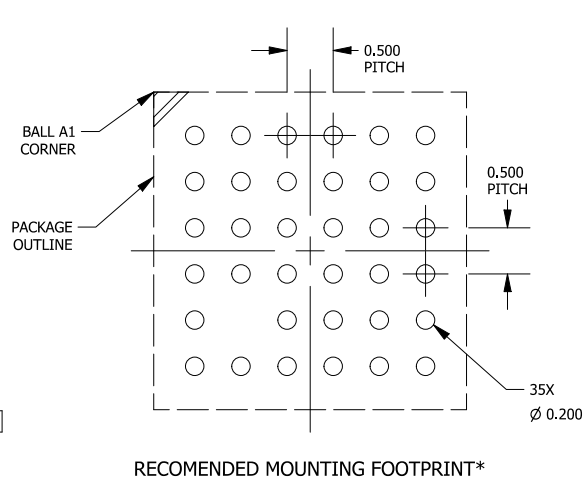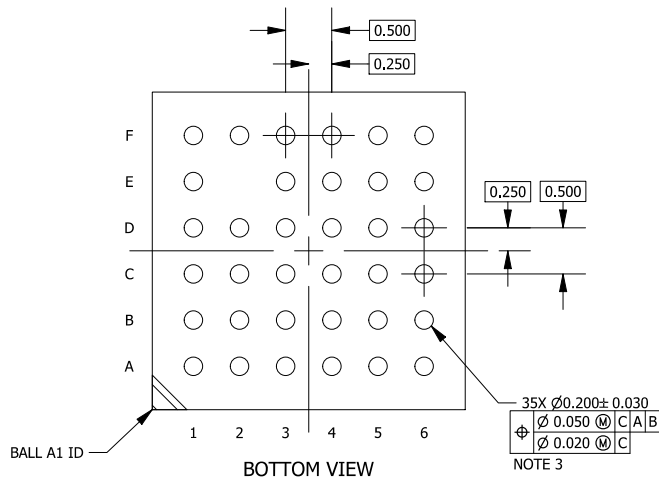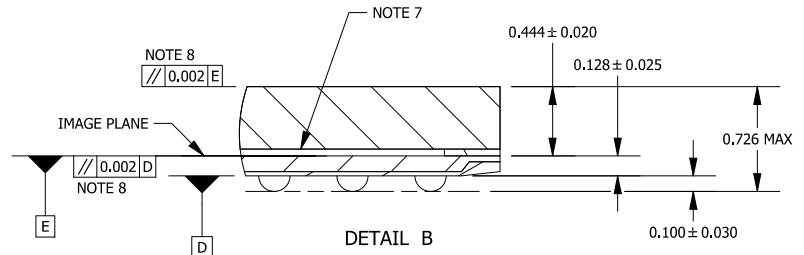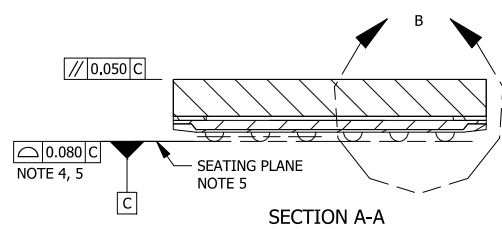
*FOR ADDITIONAL INFORMATION ON OUR Pb-FREE
STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD
THE ON SEMICONDUCTOR SOLDERING AND MOUNTING
TECHNIQUES REFERENCE MANUAL, SOLDERRM/D.

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